

Inv. Cheah Bok Eng – Innovation Unleashed – A Conversation with Malaysia Book of Record Holder

4th Mar 2024



NXP **IEEE ELECTRONICS PACKAGING SOCIETY** **IEEE**
Advancing Technology for Humanity

EVENT

INNOVATION UNLEASHED

– A CONVERSATION WITH A REMARKABLE INVENTOR –

DOOR GIFT FOR EARLY BIRDS

COME AND BE INSPIRED!

4 MARCH 2024
(MONDAY)

2.00 PM – 3.00 PM

ATKL AUDITORIUM

OUR HONORABLE SPEAKER
Inv CHEAH BOK ENG
MALAYSIA BOOK OF RECORD HOLDER
180+ ISSUED PATENTS

ALL ARE WELCOME!

- **IEEE EPS Malaysia & NXP Semiconductors Malaysia** had jointly organized an event in NXP Semiconductors Malaysia, with the presence of **Inv. Cheah Bok Eng** as the **honorable speaker, expounding on “Innovation Unleashed”**.
- Mr Cheah Bok Eng is a senior staff engineer from Intel Microelectronics. He has 190+ issued patents in the technical subject of signal integrity, advanced packaging, and system form-factor solutions. Bok Eng is a 5-time recipient of the prestigious Intel Top Inventor Awards. **He was also recognized by the Malaysia Book of Records (MBR) in 2022 as the Inventor with the Most Worldwide Patent Grants.** He is a senior member of IEEE (SMIEEE), an EXCO member of the Malaysia TRIZ Innovation Association (MyTRIZ) and the Malaysian Invention and Design Society (MINDS). He is also the author of a book titled “Innovation Unleashed... a 10-day journey with an inventor”. His unwavering dedication in promoting innovation has impacted more than 4,000 students and professionals at both national and international levels.
- Event attracted **~100 engineers with many good questions and vibrant engagement.**